

PW3599KDW

30V N-Channel + P-Channel MOSFET

-0.4A -30V; $R_{DS(ON)typ}=690m\Omega@-4.5V$, $R_{DS(ON)typ}=480m\Omega@-10V$.

0.75A30V; $R_{DS(ON)typ}=320m\Omega@4.5V$, $R_{DS(ON)typ}=290m\Omega@10V$.

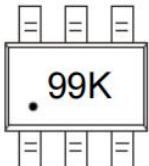
FEATURE

- Surface Mount Package
- Low $R_{DS(on)}$
- Low leakage current
- ESD Protected

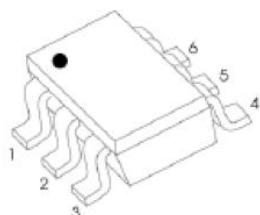
Application

- Low voltage applications
- Load/Power Switching
- Battery Management for Ultra Small Portable Electronics

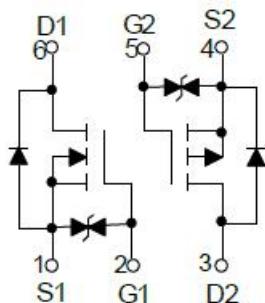
MARKING:



SOT-363



Schematic diagram



ABSOLUTE MAXIMUM RATINGS (T_a=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
P-MOSFET			
Drain-Source Voltage	V _{DS}	-30	V
Gate-Source Voltage	V _{GS}	±12	V
Continuous Drain Current ⁽¹⁾	I _D	-0.4	A
Pulsed Drain Current	I _{DM}	-1.2	A
Power Dissipation	P _D	1.4	W
N-MOSFET			
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	±12	V
Continuous Drain Current	I _D	0.75	A
Pulsed Drain Current ⁽¹⁾	I _{DM}	2.2	A
Power Dissipation	P _D	1.4	W
Temperature and Thermal Resistance			
Thermal Resistance from Junction to Ambient ⁽²⁾	R _{θJA}	89	°C/W
Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55~+150	°C

P-channel MOSFET ELECTRICAL CHARACTERISTICS($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
STATIC CHARACTERISTICS						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-30			V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}} = -30\text{V}, V_{\text{GS}} = 0\text{V}$			-1	μA
Gate-body leakage current	I_{GSS}	$V_{\text{GS}} = \pm 10\text{V}, V_{\text{DS}} = 0\text{V}$			± 10	μA
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-0.55	-1.45	-1.95	V
Drain-source on-resistance ⁽³⁾	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, I_D = -0.30\text{A}$		480	620	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_D = -0.30\text{A}$		690	900	
Forward transconductance	g_{FS}	$V_{\text{DS}} = -10\text{V}, I_D = -0.30\text{A}$		1.2		S
DYNAMIC CHARACTERISTICS⁽⁴⁾						
Input Capacitance	C_{iss}	$V_{\text{DS}} = -10\text{V}, V_{\text{GS}} = 0\text{V}, F = 1.0\text{MHz}$		120		pF
Output Capacitance	C_{oss}			18		
Reverse Transfer Capacitance	C_{rss}			9		
SWITCHING CHARACTERISTICS⁽⁴⁾						
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = -10\text{V}, I_D = -200\text{mA}, V_{\text{GS}} = -4.5\text{V}, R_G = 10\Omega$		9		nS
Turn-on rise time	t_r			6		
Turn-off delay time	$t_{\text{d}(\text{off})}$			34		
Turn-off fall time	t_f			20		
SOURCES-DRAIN DIODE CHARACTERISTICS						
Diode forward voltage	V_{DS}	$I_S = -0.4\text{A}, V_{\text{GS}} = 0\text{V}$			-1.2	V

N-channel MOSFET ELECTRICAL CHARACTERISTICS($T_a=25^\circ\text{C}$ unless otherwise noted)

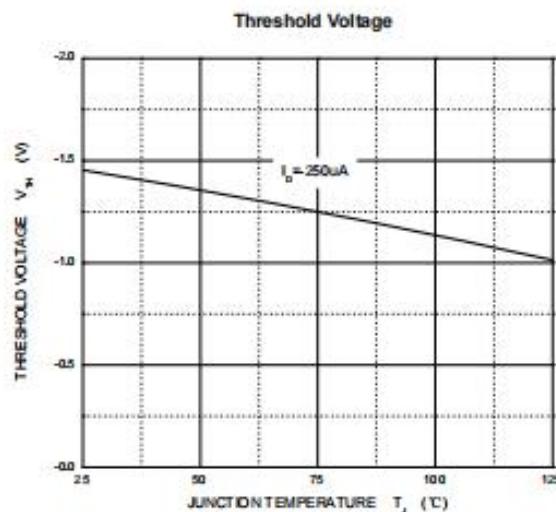
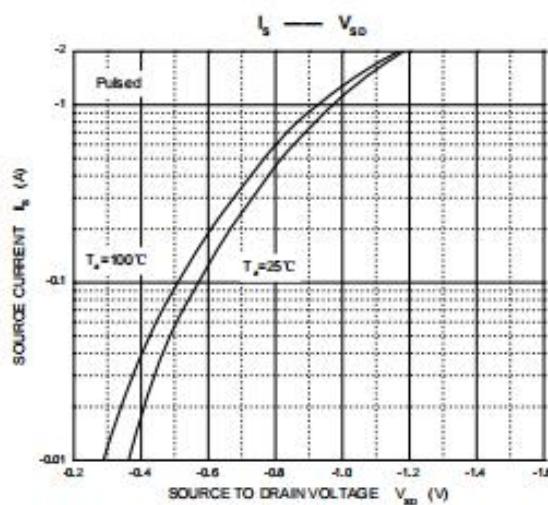
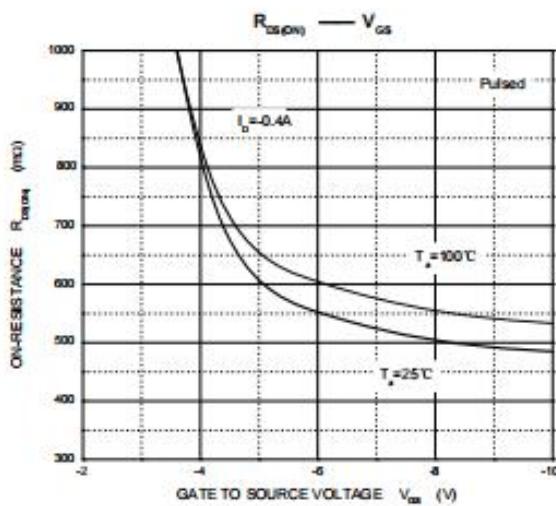
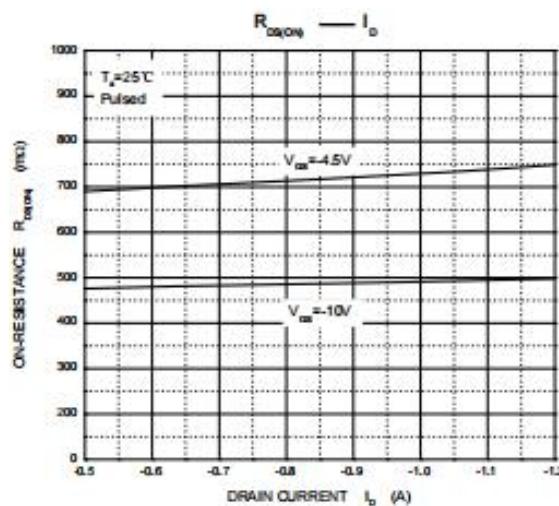
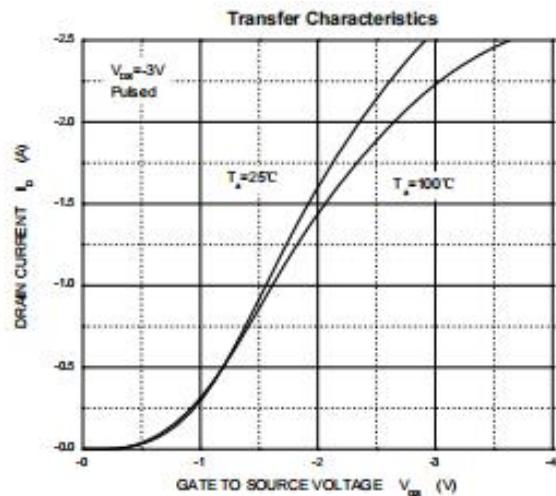
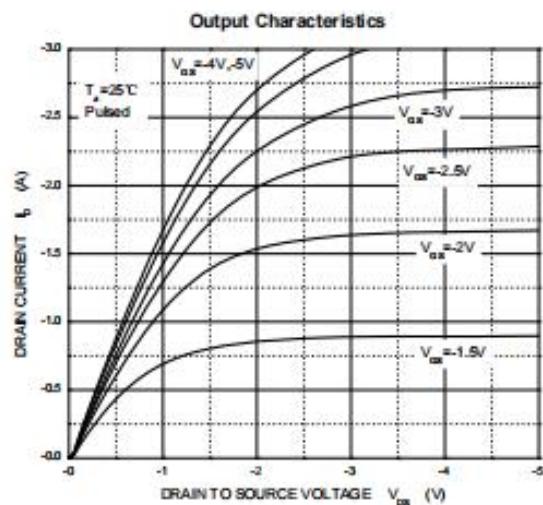
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
STATIC CHARACTERISTICS						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30			V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
Gate-body leakage current	I_{GSS}	$V_{\text{GS}} = \pm 10\text{V}, V_{\text{DS}} = 0\text{V}$			± 3	μA
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	0.5	1.0	1.5	V
Drain-source on-resistance ⁽³⁾	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 0.6\text{A}$		290	370	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 0.6\text{A}$		320	420	
Forward transconductance	g_{FS}	$V_{\text{DS}} = 5\text{V}, I_D = 0.5\text{A}$		0.9		S
DYNAMIC CHARACTERISTICS⁽⁴⁾						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 10\text{V}, V_{\text{GS}} = 0\text{V}, F = 1.0\text{MHz}$		44		pF
Output Capacitance	C_{oss}			15		
Reverse Transfer Capacitance	C_{rss}			8		
SWITCHING CHARACTERISTICS⁽⁴⁾						
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 10\text{V}, I_D = 0.7\text{A}$ $V_{\text{GS}} = 4.5\text{V}, R_{\text{GEN}} = 51\Omega$		5		nS
Turn-on rise time	t_r			8		
Turn-off delay time	$t_{\text{d}(\text{off})}$			23		
Turn-off fall time	t_f			41		
SOURCES-DRAIN DIODE CHARACTERISTICS						
Diode forward voltage	V_{DS}	$I_s = 0.6\text{A}, V_{\text{GS}} = 0\text{V}$		0.87	1.2	V

Notes:

- 1.Repetitive Rating : Pulse width limited by maximum junction temperature.
- 2.Surface Mounted on FR4 Board, $t < 5$ sec.
- 3.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
- 4.Guaranteed by design, not subject to production testing.

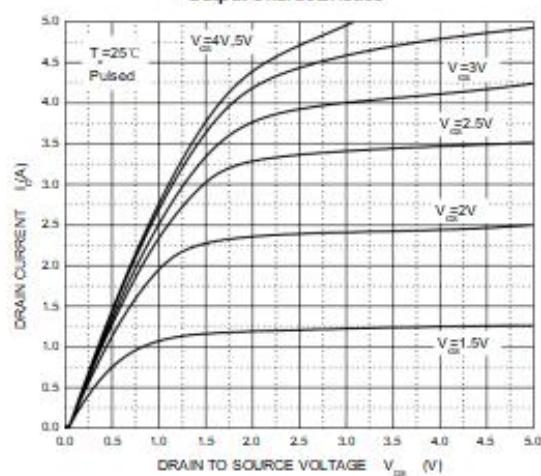
Typical Electrical and Thermal Characteristics

P-Channel MOS

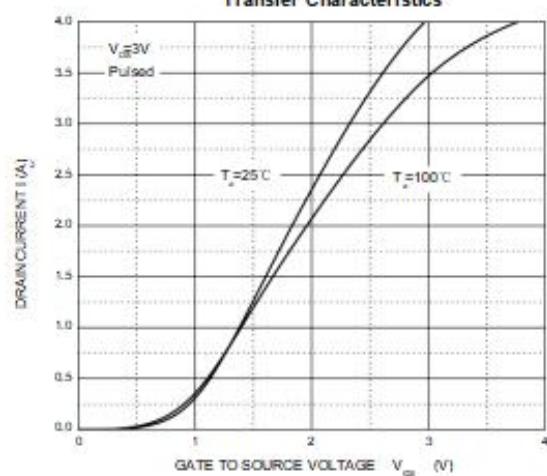


N-Channel MOS

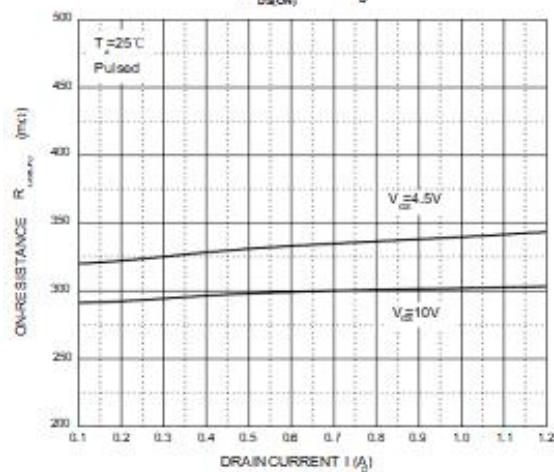
Output Characteristics



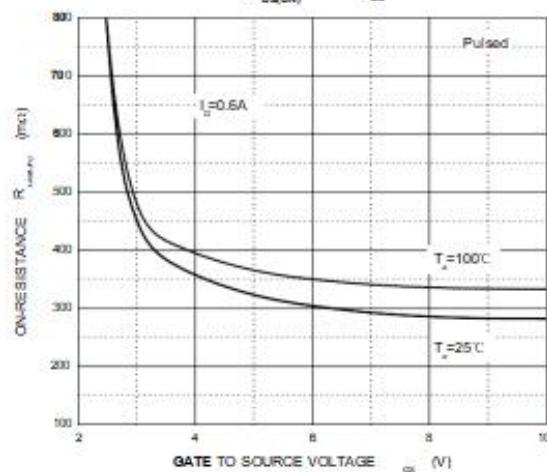
Transfer Characteristics



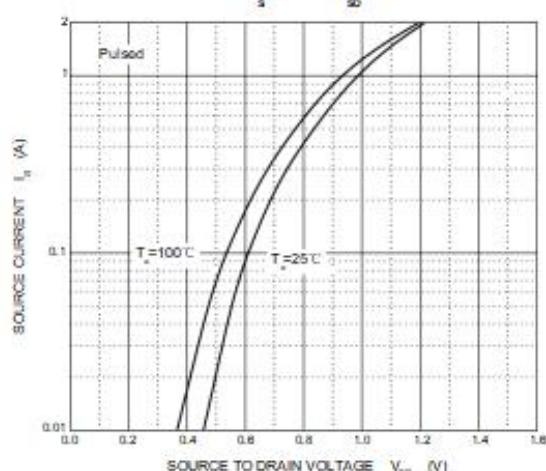
$R_{DS(on)} - I_D$



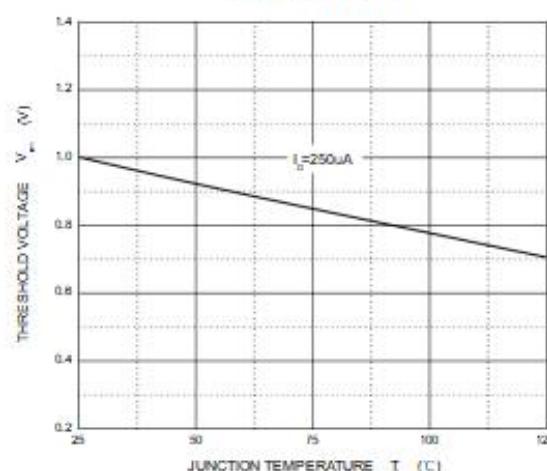
$R_{DS(on)} - V_{GS}$

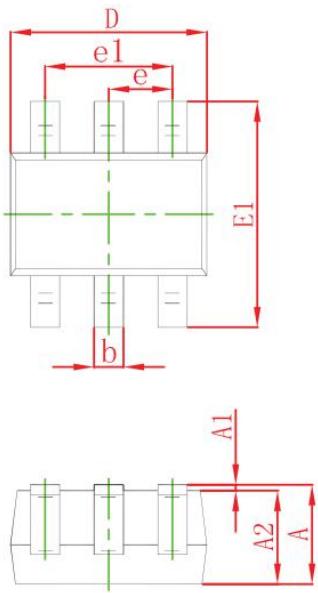


$I_s - V_{SD}$



Threshold Voltage

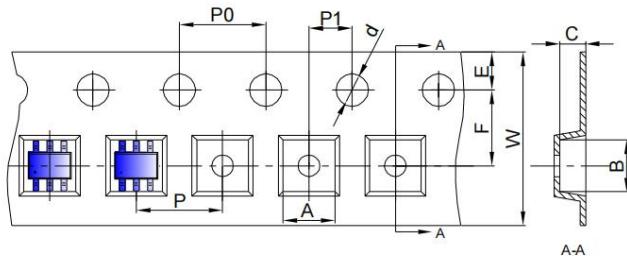




Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
c	0.100	0.150	0.004	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.400	0.085	0.094
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

SOT-363 Tape and Reel

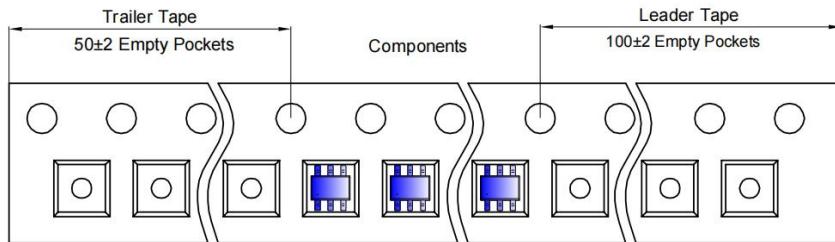
SOT-363 Embossed Carrier Tape



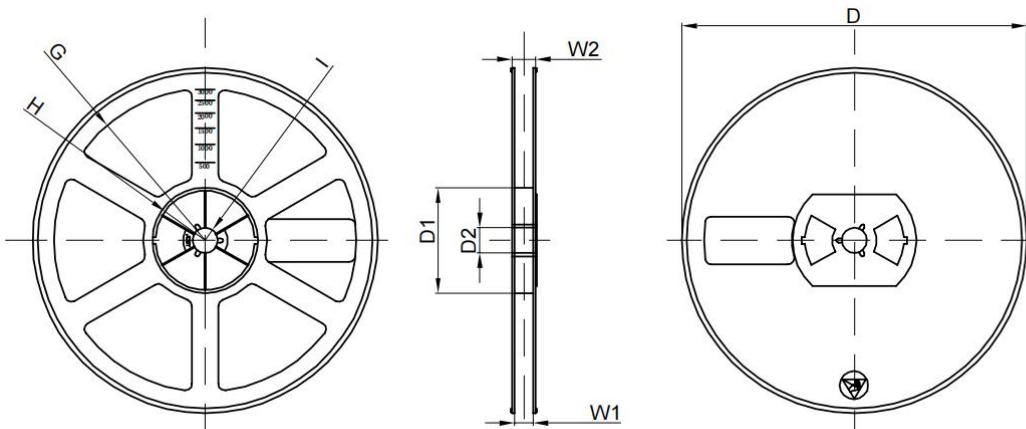
Dimensions are in millimeter

Pkg type	A	B	C	d	E	F	P0	P	P1	W
SOT-363	2.55	2.55	1.20	Ø1.50	1.75	3.50	4.00	4.00	2.00	12.00

SOT-363 Tape Leader and Trailer



SOT-363 Reel



Dimensions are in millimeter

Reel Option	D	D1	D2	G	H	I	W1	W2
7" Dia	Ø178.00	54.40	13.00	R78.00	R25.60	R6.50	9.50	12.30

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
3000 pcs	7 inch	30,000 pcs	203×203×195	120,000 pcs	438×438×220	